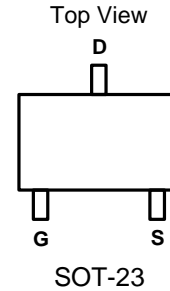


P-Channel Enhancement Mode MOSFET

Features

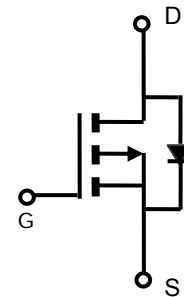
- -30V/-4.3A, $R_{DS(ON)} = 50m\Omega @ V_{GS} = -10V$
- -30V/-3.5A, $R_{DS(ON)} = 60m\Omega @ V_{GS} = -4.5V$
- -30V/-2.5A, $R_{DS(ON)} = 80m\Omega @ V_{GS} = -2.5V$
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and Maximum DC current capability
- This is a Full RoHS compliance
- SOT-23L package design

Pin Description





Applications

- Power Management in Note book
- Portable Equipment
- DSC
- LCD Display inverter
- Battery Powered System
- DC/DC Converter
- Load Switch



P Channel MOSFET

Ordering and Marking Information

<p>AM3401 </p> <p>  </p> <p>Packing Type</p> <p>Package Code</p>	<p>Package R : SOT23-3L</p> <p>Packing Blank : Tube A : Taping</p>
<p>AM3401 : B1XXX</p>	<p>XXX - Date Code</p>

Note: AXElite lead-free products contain molding compounds/die attach materials and 100% matte tin plate termination finish; which are fully compliant with RoHS. AXElite lead-free products meet or exceed the lead-free requirements of IPC/JEDEC J-STD-020C for MSL classification at lead-free peak reflow temperature. AXElite defines "Green" to mean lead-free (RoHS compliant) and halogen free (Br or Cl does not exceed 900ppm by weight in homogeneous material and total of Br and Cl does not exceed 1500ppm by weight).

Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Rating	Unit	
V_{DSS}	Drain-Source Voltage	-30	V	
V_{GSS}	Gate-Source Voltage	± 12		
I_D	Continuous Drain Current ($T_J=150^\circ\text{C}$)	$V_{GS} = -10\text{V}$ -4.3	A	
I_{DM}	Pulsed Drain Current			-15
I_S	Continuous Source Current (Diode Conduction)	-1	A	
T_J	Maximum Junction Temperature	150	$^\circ\text{C}$	
T_{STG}	Storage Temperature Range	-55 to 150		
P_D	Maximum Power Dissipation	$T_A=25^\circ\text{C}$	1.25	W
		$T_A=70^\circ\text{C}$	0.8	
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient	120	$^\circ\text{C/W}$	

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged.
Absolute maximum ratings are stress ratings only and functional device operation is not implied.

Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
Static Parameters						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=-250\mu\text{A}$	-30			V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu\text{A}$	-0.4		-1.0	V
I_{GSS}	Gate Leakage Current	$V_{DS}=0\text{V}, V_{GS}=\pm 12\text{V}$			± 100	nA
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-24\text{V}, V_{GS}=0\text{V}$			-1	μA
		$V_{DS}=-24\text{V}, V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$			-10	
$R_{DS(ON)}$	Drain-source On-Resistance	$V_{GS}=-10\text{V}, I_D=-4.3\text{A}$ $V_{GS}=-4.5\text{V}, I_D=-3.5\text{A}$ $V_{GS}=-2.5\text{V}, I_D=-2.5\text{A}$		50 60 80	55 65 85	m Ω
G_{fs}	Forward Transconductance	$V_{DS}=-5\text{V}, I_D=-4.0\text{A}$		10		S
Source-Drain Diode						
V_{SD}	Diode Forward Voltage	$I_S=-1.0\text{A}, V_{GS}=0\text{V}$		-0.8	-1.2	V
Dynamic Parameters						
Q_g	Total Gate Charge	$V_{DS}=-15\text{V}$ $V_{GS}=-10\text{V}$ $I_D=-4.0\text{A}$		6		nC
Q_{gs}	Gate-Source Charge			12		
Q_{gd}	Gate-Drain Charge			1.5		
C_{iss}	Input Capacitance	$V_{DS}=-15\text{V}$ $V_{GS}=0\text{V}$ $f=1\text{MHz}$		815		pF
C_{oss}	Output Capacitance			93		
C_{rss}	Reverse Transfer Capacitance			52		
$t_{d(on)}$	Turn-On Time	$V_{DD}=-15\text{V}$ $R_L=15\Omega$ $I_D=-1\text{A}$ $V_{GEN}=-10\text{V}$ $R_G=6\Omega$		10	15	nS
t_r				2	5	
$t_{d(off)}$	Turn-Off Time			31	40	
t_f			3	6		

Note : 1. Pulse test: pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
2. Static parameters are based on package level with recommended wire-bonding

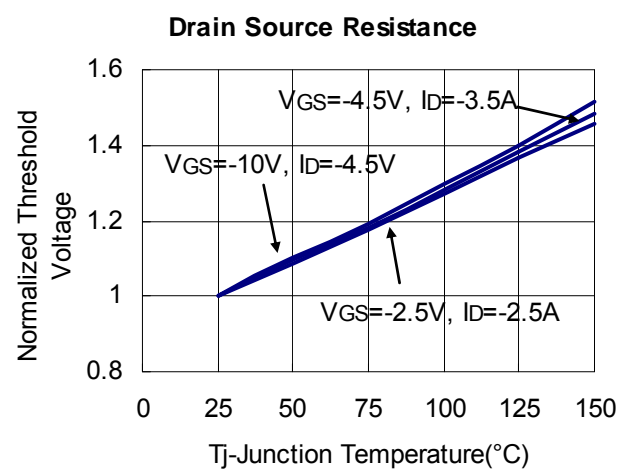
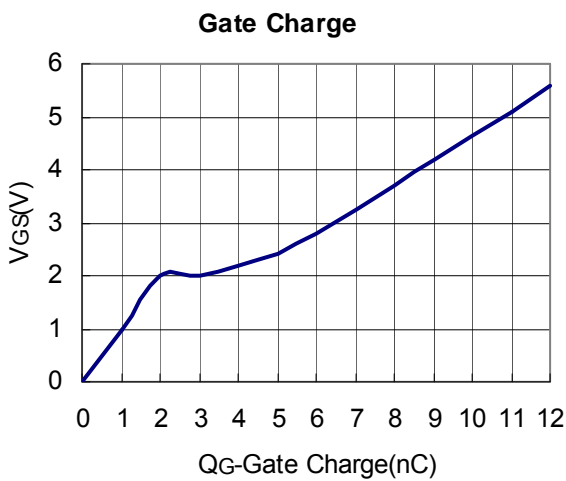
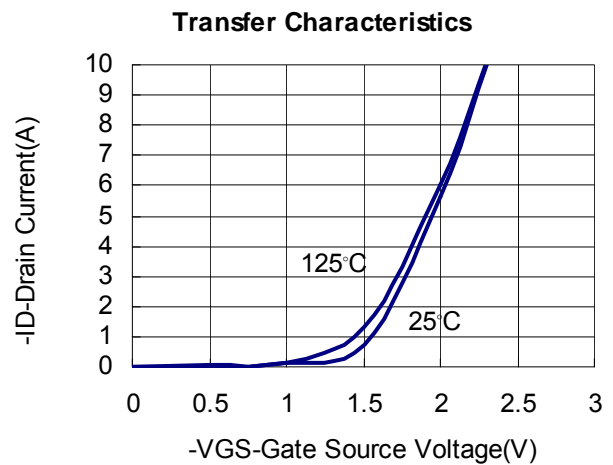
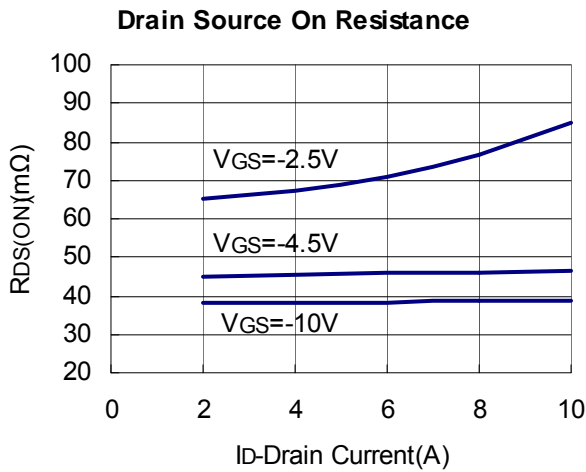
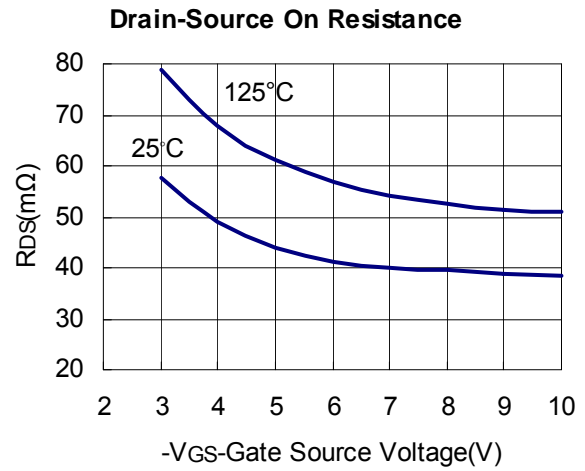
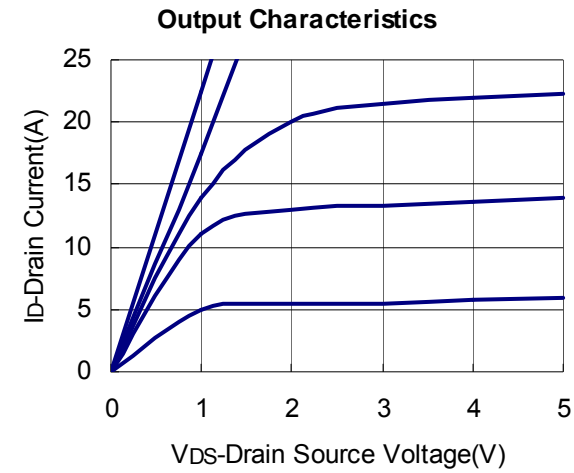
Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
Static Parameters						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-30			V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu A$	-0.4		-1.0	V
I_{GSS}	Gate Leakage Current	$V_{DS}=0V, V_{GS}=\pm 12V$			± 100	nA
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-24V, V_{GS}=0V$			-1	μA
		$V_{DS}=-24V, V_{GS}=0V$ $T_J=55^\circ C$			-10	
$R_{DS(ON)}$	Drain-source On-Resistance	$V_{GS}=-10V, I_D=-4.3A$		50	55	m Ω
		$V_{GS}=-4.5V, I_D=-3.5A$		60	65	
		$V_{GS}=-2.5V, I_D=-2.5A$		80	85	
G_{fs}	Forward Transconductance	$V_{DS}=-5V, I_D=-4.0A$		10		S
Source-Drain Diode						
V_{SD}	Diode Forward Voltage	$I_S=-1.0A, V_{GS}=0V$		-0.8	-1.2	V
Dynamic Parameters						
Q_g	Total Gate Charge	$V_{DS}=-15V$ $V_{GS}=-10V$ $I_D=-4.0A$		6		nC
Q_{gs}	Gate-Source Charge			12		
Q_{gd}	Gate-Drain Charge			1.5		
C_{iss}	Input Capacitance	$V_{DS}=-15V$ $V_{GS}=0V$ $f=1MHz$		815		pF
C_{oss}	Output Capacitance			93		
C_{rss}	Reverse Transfer Capacitance			52		
$t_{d(on)}$	Turn-On Time	$V_{DD}=-15V$ $R_L=15\Omega$ $I_D=-1A$ $V_{GEN}=-10V$ $R_G=6\Omega$		10	15	nS
t_r				2	5	
$t_{d(off)}$	Turn-Off Time			31	40	
t_f				3	6	

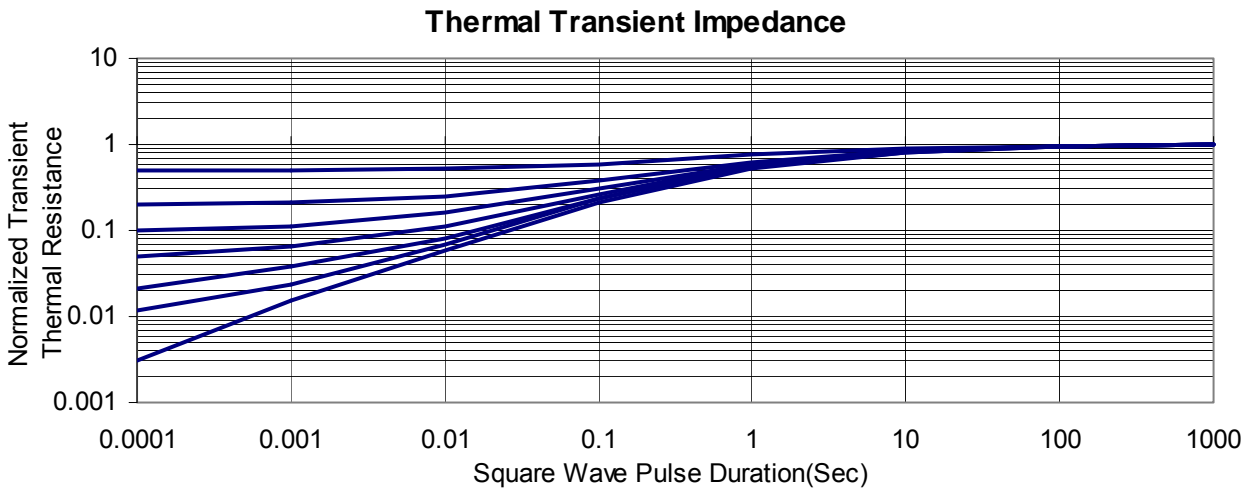
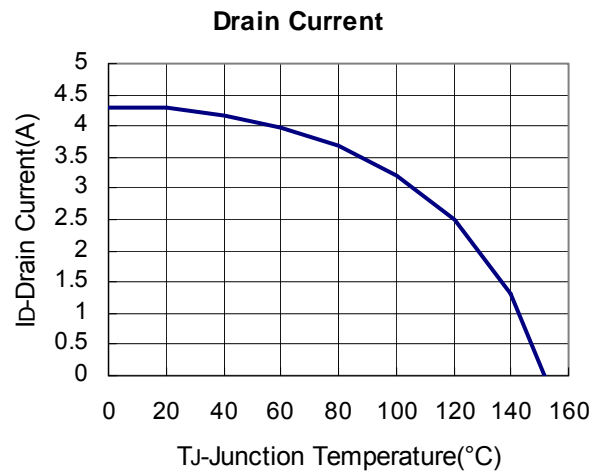
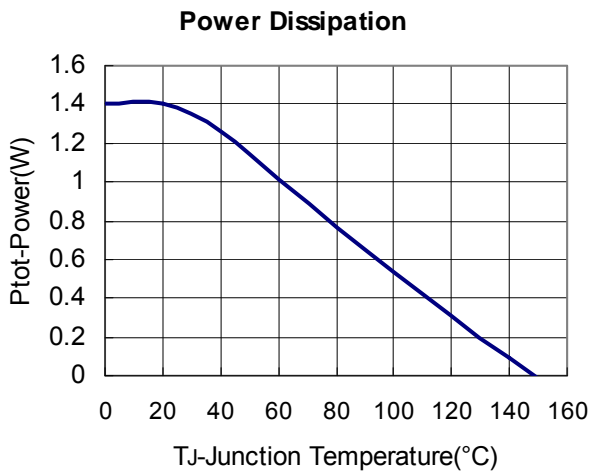
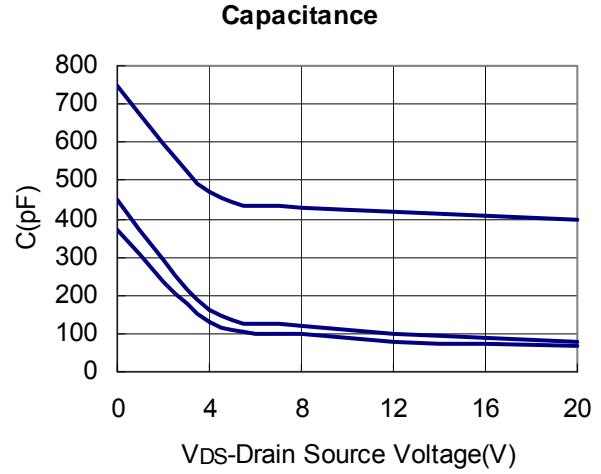
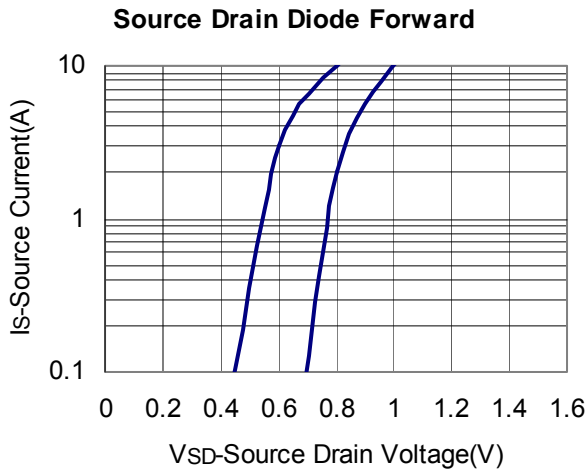
Note : 1. Pulse test: pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$

2. Static parameters are based on package level with recommended wire-bonding

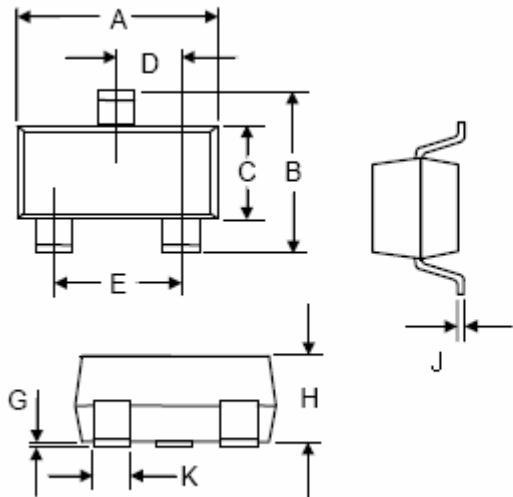
Typical Operating Characteristics (25°C Unless Note)



Typical Operating Characteristics (25°C Unless Note)



SOT-23L PACKAGE DIMENSIONS



Symbol	Dimensions			
	Inches		Millimeters	
	Min	Max	Min	Max
A	0.110	0.120	2.80	3.04
B	0.104	0.116	2.65	2.95
C	0.059	0.067	1.50	1.70
D	0.037 TYP		0.95 TYP	
E	0.70	0.081	1.78	2.05
G	---	0.004	---	0.10
H	0.041	0.045	1.05	1.15
J	0.004	0.008	0.10	0.20
K	0.012	0.16	0.30	0.40